

TITLE

PROCESS FOR REMOVING AN ORGANIC LAYER DURING
FABRICATION OF AN ORGANIC ELECTRONIC DEVICE AND THE
ORGANIC ELECTRONIC DEVICE FORMED BY THE PROCESS

5 ABSTRACT OF THE DISCLOSURE

 A method of dry etching a performance sensitive element of an
organic electronic device, said method comprising the steps of: (a) having
at least one performance sensitive element on the substrate spaced apart
from a first conductive member, wherein at least one of the performance
10 sensitive elements is a conductive lead; (b) placing organic material on the
performance sensitive element and the first conductive member;
(c) forming a patterned conductive layer over the organic material
exposing a predetermined portion of the performance sensitive elements;
and (d) dry etching the organic material in the exposed areas of the
15 performance sensitive elements using at least one oxygen-containing gas,
and organic electronic device created using said process.

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35 MAC/dmm